SOIC6 W
CASE 751EM
ISSUE 0

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MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

NOTES: UNLESS OTHERWISE SPECIFIED
A) NO STANDARD APPLIES TO THIS PACKAGE
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONS DO NOT INCLUDE BURRS
   OR MOLD FLASH, AND TIE BAR EXTRUSION.
D) DIMENSIONING AND TOLERANCING PER

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